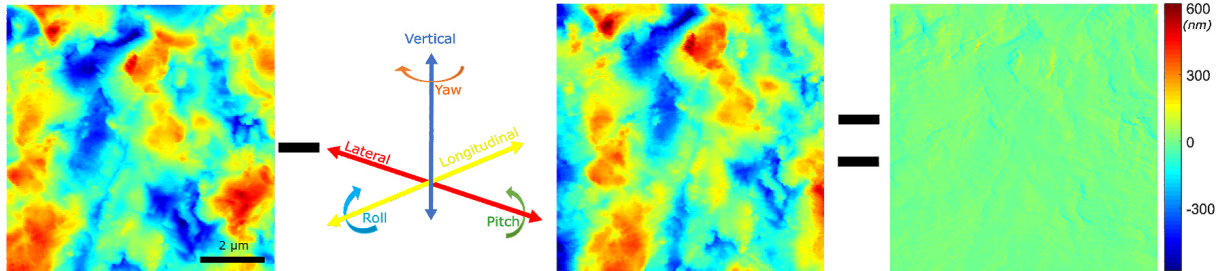


Measuring nanowear

Friction and wear are of crucial importance in chip production. As the dimensions of features in chips shrink, so do the requirements in terms of wear and friction for the positioners that handle silicon wafers. In this project, you will study measurements of surfaces that have been subjected to wear. Comparing the before and after-wear test measurements will indicate where the wear events took place and how much material was removed. The goal of the project will be to optimize the script that is used to compare surface topographies before and after wear took place.



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